

PCN Tracking Number: PCN_FT_022

Issue Date: 2015-11-20

Product Change Notification: For Limited Distribution

Product Part Number	Vinculum-II devices : VNC2-32L1B, VNC2-32Q1B, VNC2-48Q1B, VNC2-48L1B, VNC2-64Q1B, VNC2-64L1B	Estimated implementation date
Description of Change	Device revised from Revision B to Revision C	Dec 2015
Reason for Change	To improve ESD susceptibility.	
Detailed Description	The grounding, within the package of the VNC2 device, has been modified to improve its ESD susceptibility.	
Impact to Data sheet	No change to datasheet	
Benefit of Change	Improved tolerance to ESD, resulting in higher quality of devices.	
Markings to distinguish revised from:	Devices will be marked as with a "C" to indicate Revision C: VNC2-32L1C, VNC2-32Q1C, VNC2-48L1C, VNC2-48Q1C, VNC2-64L1C, VNC2-64Q1C,	
Sample Availability	Jan 2016	
Risk Assessment, Fit Form and Function & reliability	Fit: package dimensions are unchanged Form : visual appearance is unchanged Function: Functional silicon has not changed.	
PDF Download	http://www.ftdichip.com/Support/Documents/ProductChangeNotifications/PCN_FT_022.pdf	
Others: The Vinculum-II VNC2 Revision B and VNC2 Revision C silicon is exactly the same. There are no functional changes to the IC.		